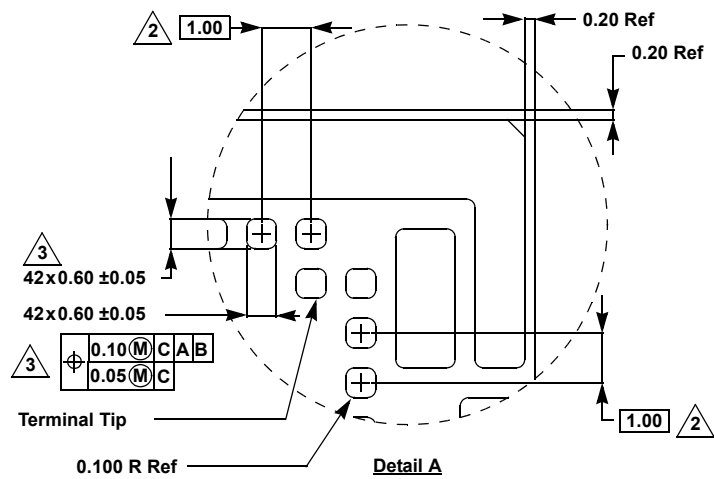
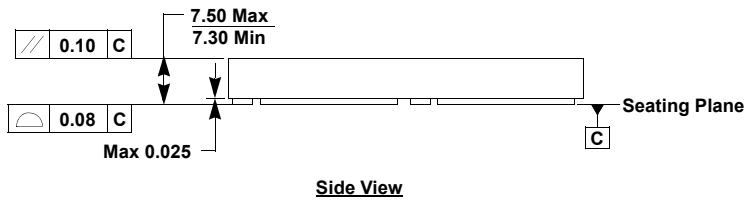
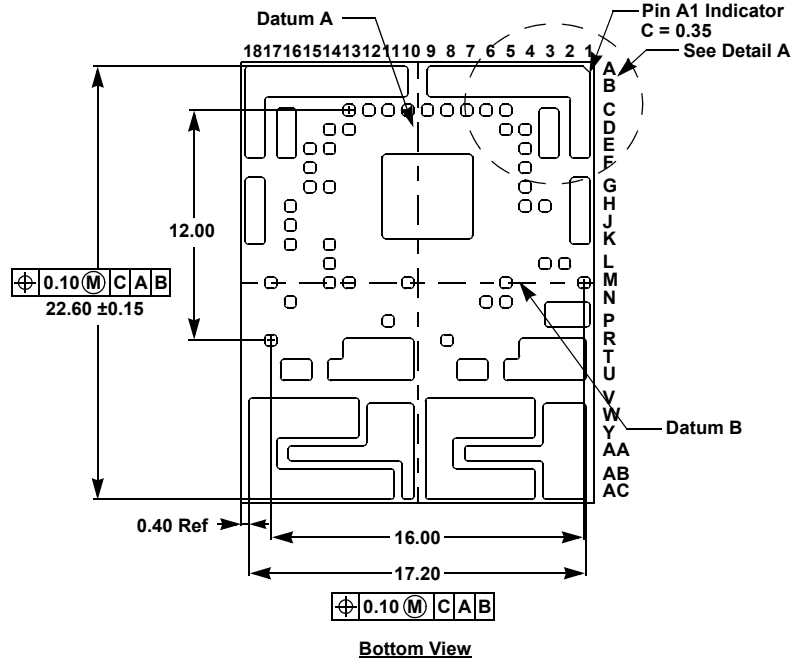
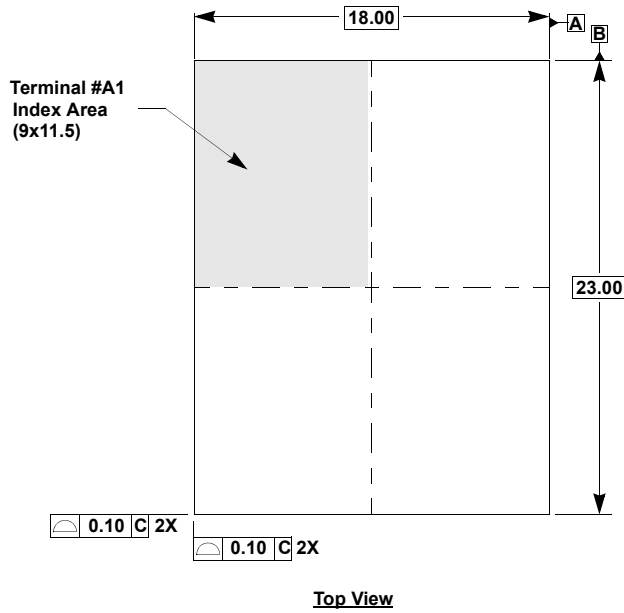


Package Outline Drawing

Y58.18x23

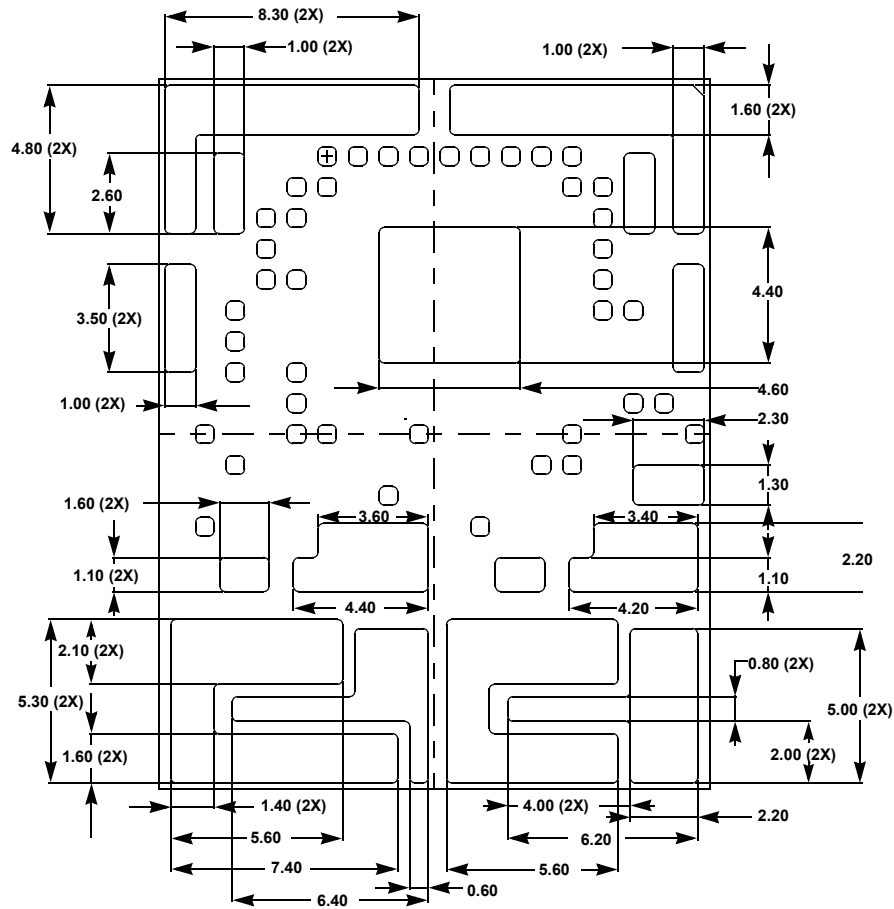
58 I/O 18mmx23mmx7.5mm Custom HDA Module

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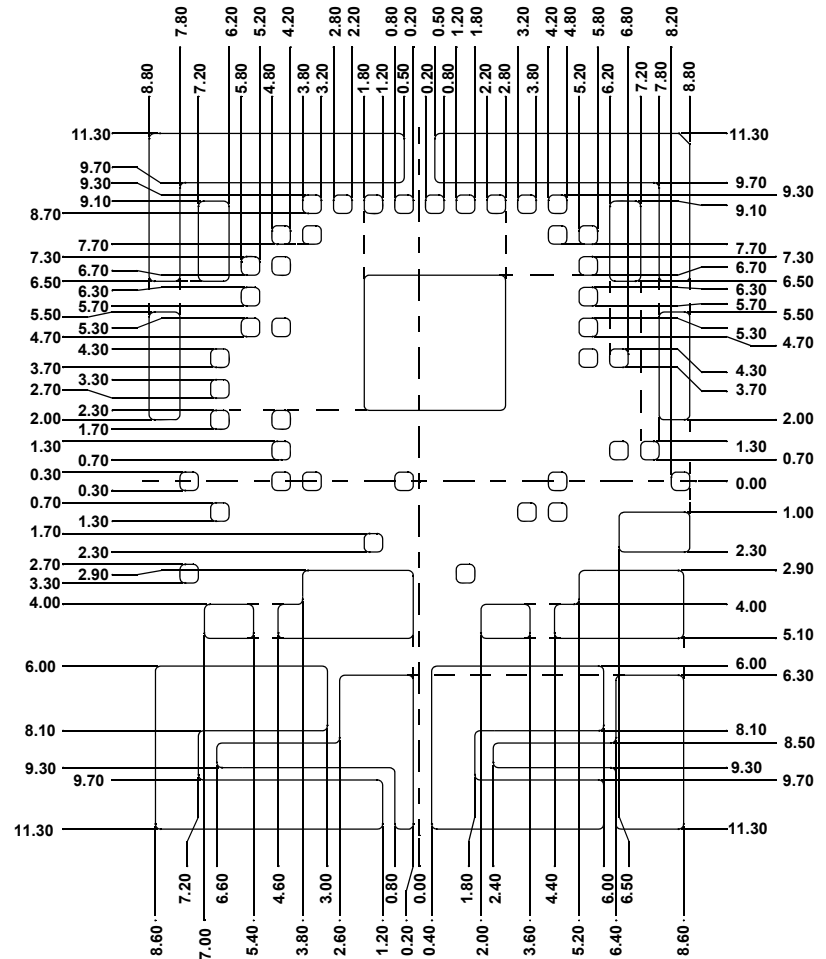


Notes:

1. All dimensions are in millimeters.
2. Represents the basic land grid pitch.
3. These 42 I/Os are centered in a fixed row and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5-2009.
5. Tolerance for exposed PAD edge location dimension on page 3 is ±0.1mm.

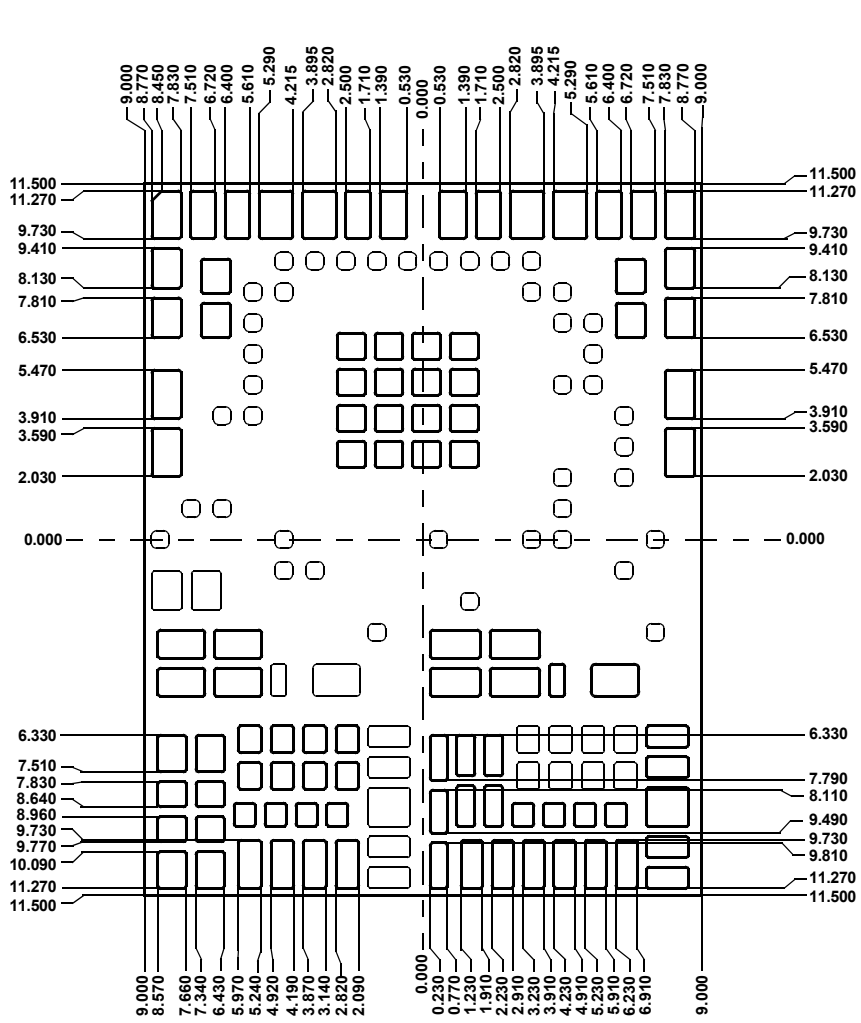


Size Details for the 16 Exposed Pads

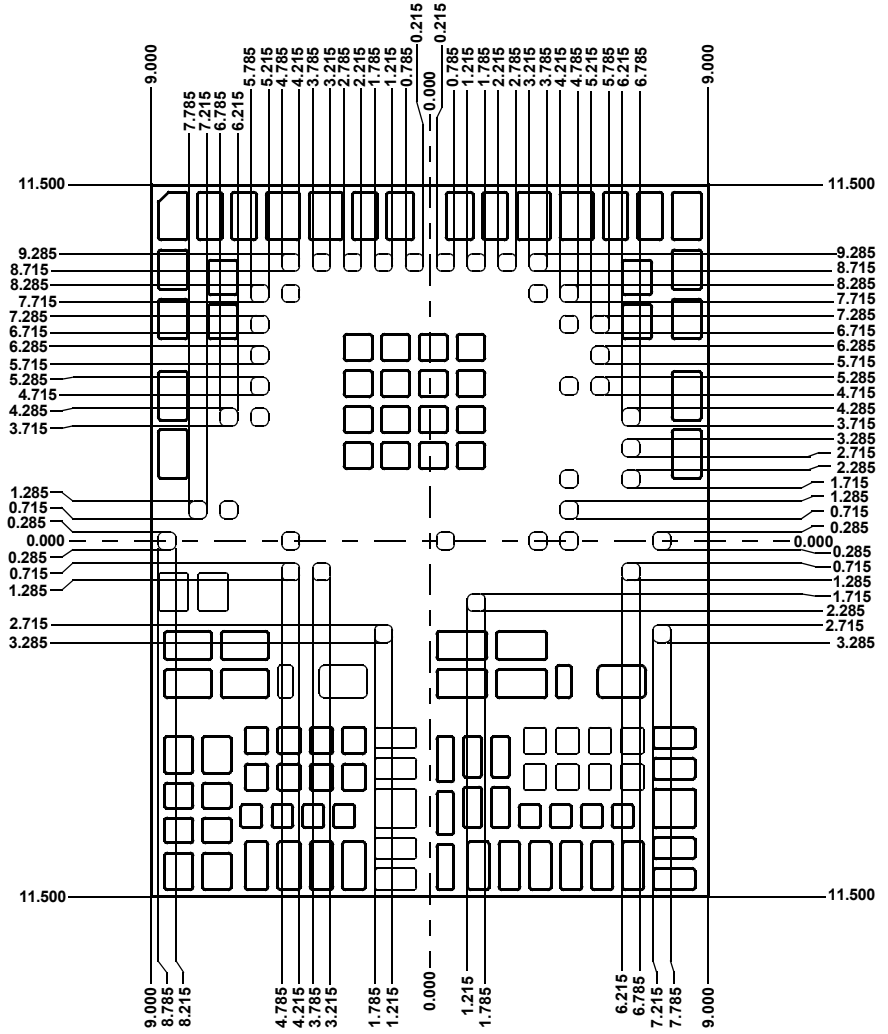


Terminal and Pad Edge Details

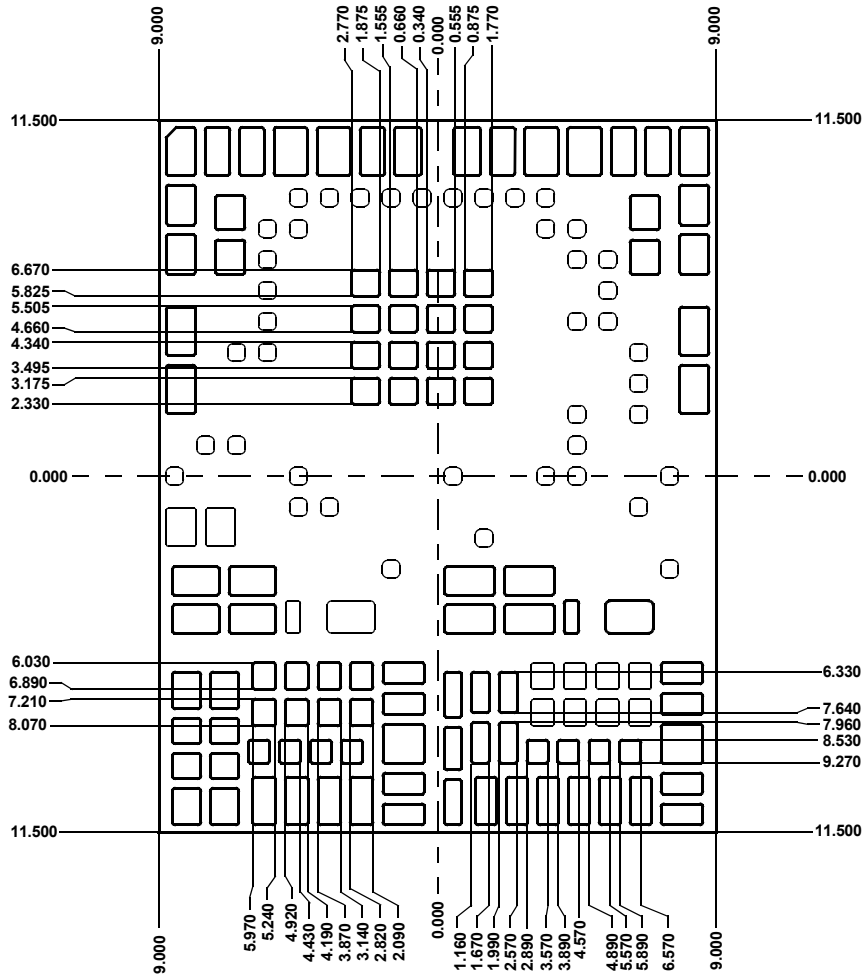
Bottom View



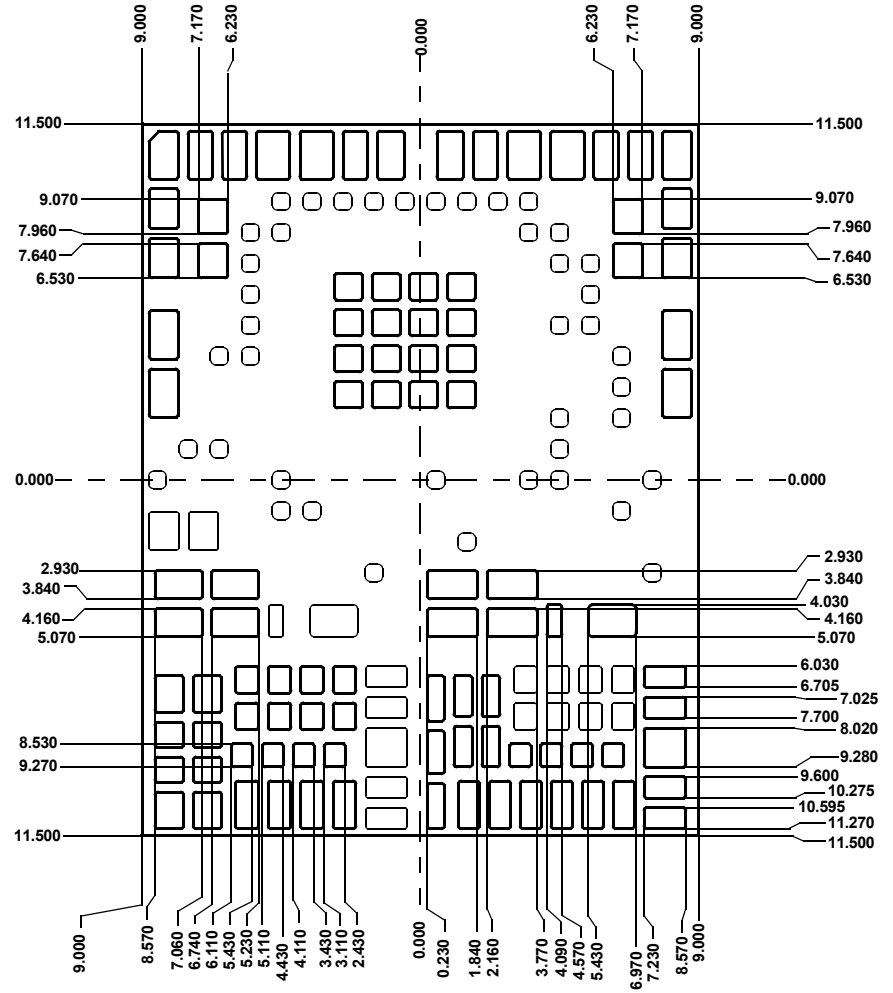
Stencil Opening Edge Position - 1



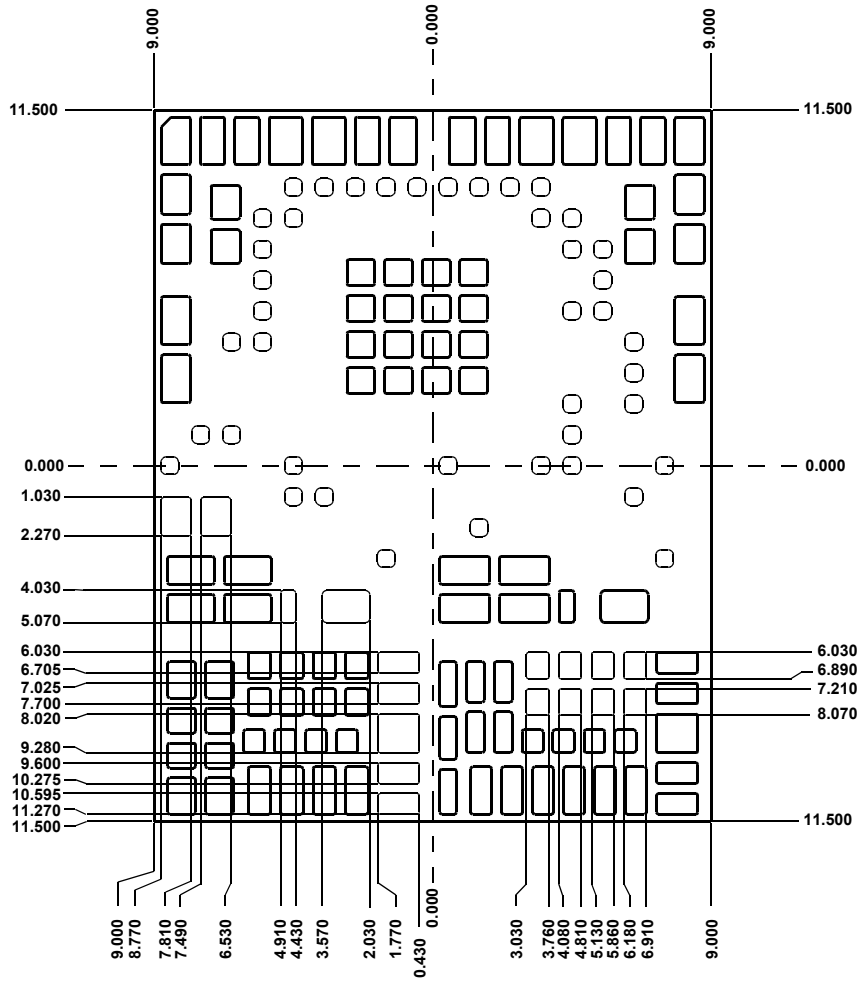
Stencil Opening Edge Position - 2



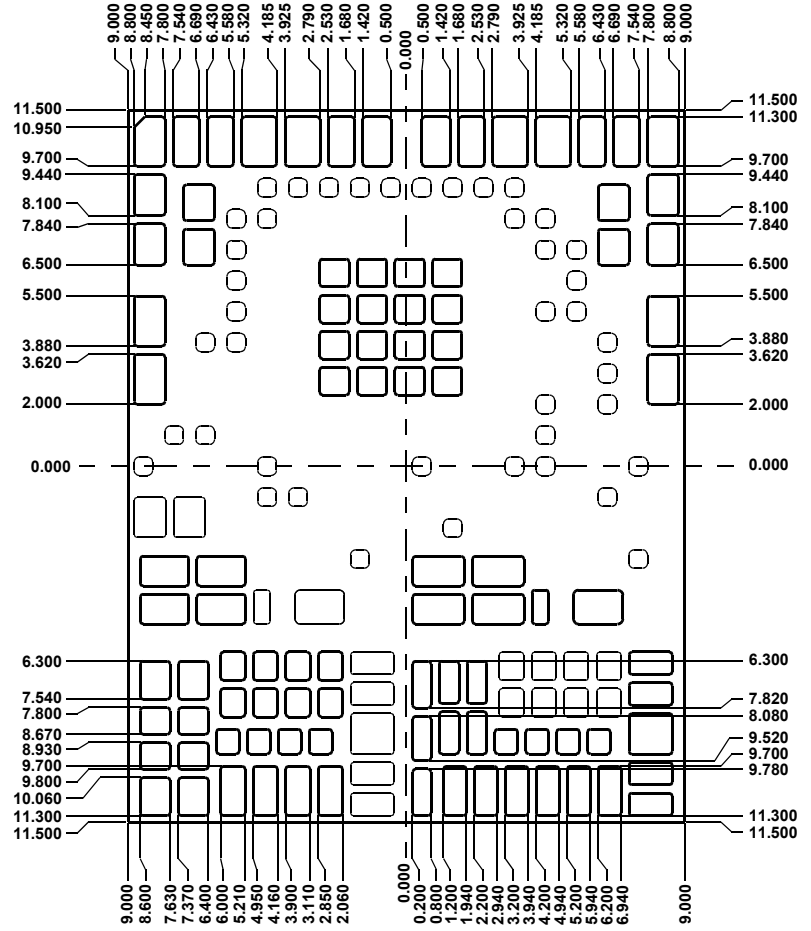
Stencil Opening Edge Position - 3



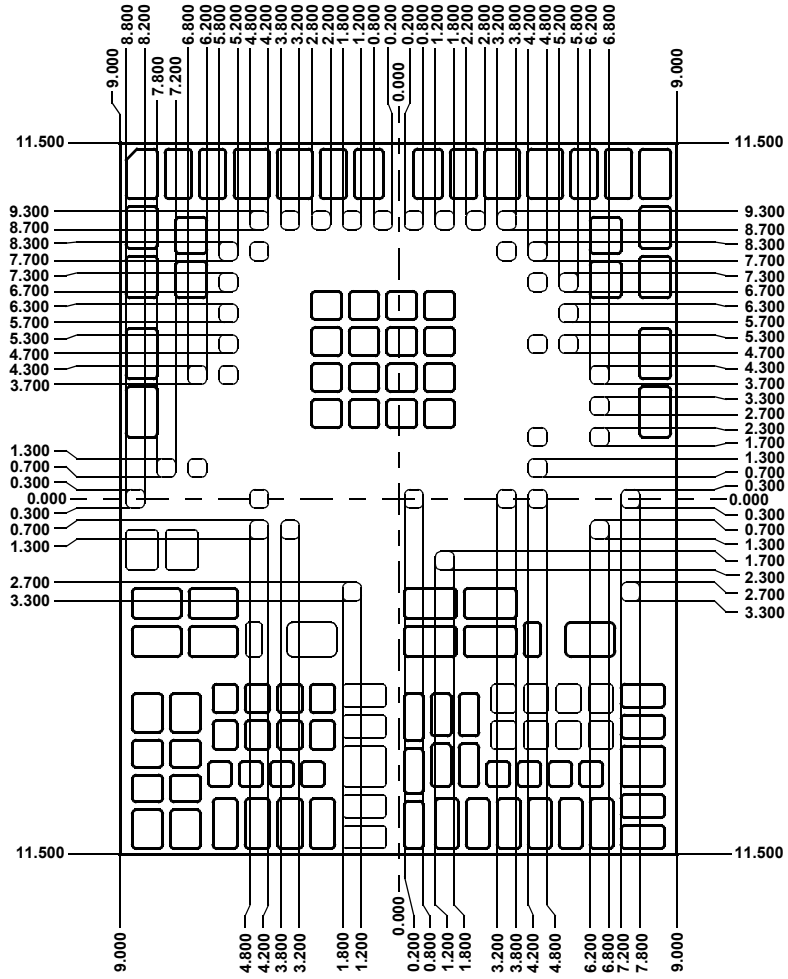
Stencil Opening Edge Position - 4



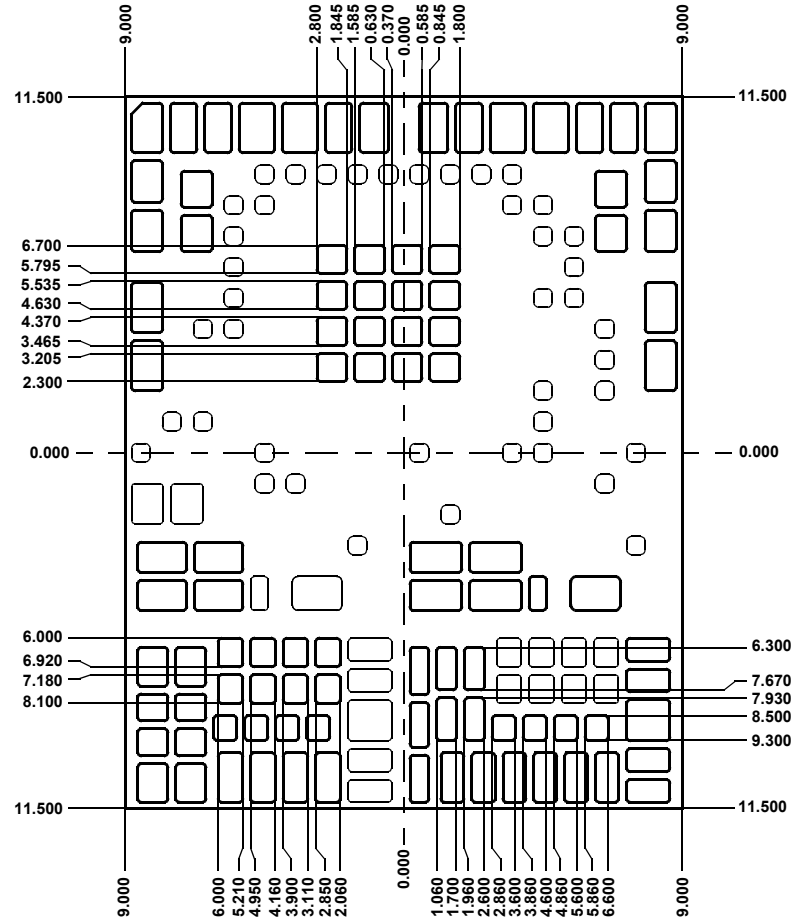
Stencil Opening Edge Position - 5



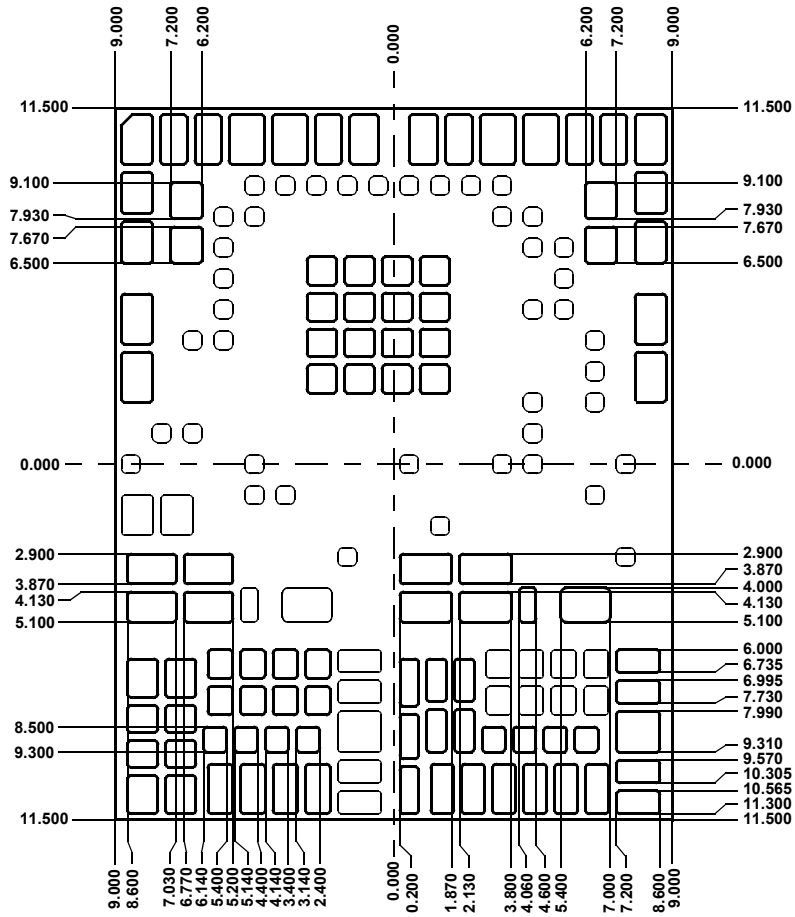
PCB Land Pattern - 1 (for Reference)



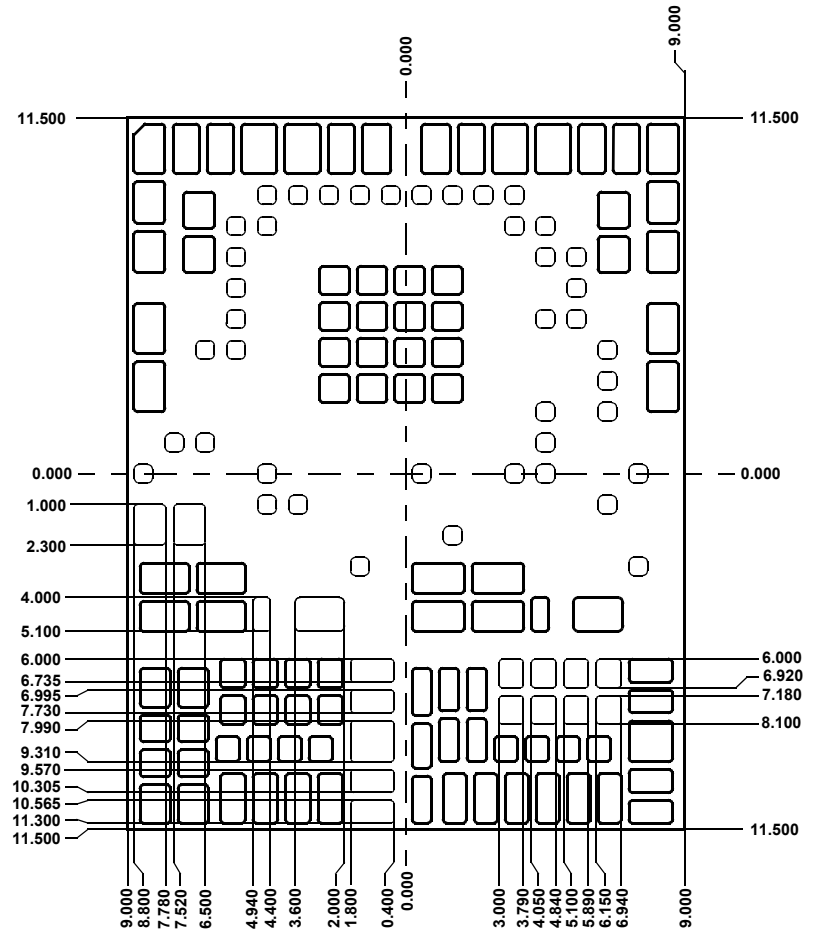
PCB Land Pattern - 2 (for Reference)



PCB Land Pattern - 3 (for Reference)



PCB Land Pattern - 4 (for Reference)



PCB Land Pattern - 5 (for Reference)